

Claims

[Claim 1]

A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of either palladium alloy or beryllium copper alloy.

[Claim 2]

A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of either palladium alloy or beryllium copper alloy and a wire drawing operation with a wire drawing die is performed.

[Claim 3]

A probe for a probe card according to claim 1 characterized in that a gold plating is applied to the upper-most surface of said probe.

[Claim 4]

A probe for a probe card according to claim 2 characterized in that a gold plating is further applied to the upper-most surface of said probe after said wire drawing operation is performed.